

1 **DEVICE, DESIGN AND METHOD FOR A SLOT IN A CONDUCTIVE AREA**

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Abstract

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5 A design, device, system and process for placing slots in active regions
6 (e.g., metal areas). Embodiments of the present invention improve the planarization of
7 metal areas (e.g., lines) and insulators by reducing depressions (e.g., dishing) in the metal
8 areas by including symmetric or square slots inside selected wide metal lines, by adhering
9 to a set of placement rules. Embodiments reduce dishing in copper dual damascene
10 structures. Embodiments reduce data processing requirements for designing and arranging
11 the layout of IC devices and the slots.

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(Figure 2)